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100% Solid
Low Temperature Curable
Snap-Curable
Long Pot-Life
Fine Pitch with Extra-Fine Silver

IDEAL FOR:

- In-line Die-Attach
- Large and Small Dies
- Rapid Curing for Smaller Dies (<10mm)
- Low Temperature Curing for Large Dies

DESCRIPTION:

ME8630-SSC is a ultra-fast curing with extra fine silver filled for finer pitch application. It is a low stress, low temperature curable die-attach adhesive paste. This single component, silver filled paste is electrically and thermally conductive. It is highly thixotropic with outstanding compatibility for bonding different adherends. The relatively medium Tg and modulus made it suitable for bonding both smaller and relatively large devices. Wire-bonding at temperatures as high as 250°C is easily achievable.

ME8630-SSC has been designed to eliminate bleeding on both silver plated copper and alloy 42 leadframes.

AVAILABILITY:

ME8630-SSC is available in syringes for automatic needle dispense applications or in jars.

APPLICATION PROCEDURES:

- (1) Thaw to ambient temperature for 30 minutes before opening jar or using syringes.
- (2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- (3) Cure according to one of the recommended cure schedules.

Snap Curing Die-Attach
ME8630-SSC

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 5 min)	<5x10⁻⁴ ohm-cm
Dielectric Strength (Volts/mil)	>Not Applicable
Glass Transition Temp.(°C)	80 ±10%
Current Carrying Capabilities	>20 Amp/mm²
Lap-Shear Strength	>NA
Device Push-off Strength	>2000 psi >10.39 N/mm²
Hardness (Type)	80 (D) ±10%
Cured Density (gm/cc)	4.0 ±10%
Thermal Conductivity	>80 Btu-in/hr-ft²-°F ±10% >11.5 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	40 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(5 rpm, 25°C) (Brookfield DV-1,Spindle CP51)	60,000 cp ±20% 3.5-4.5

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

Temperature	Time	Pressure
50°C	2 hr	
90°C	30 min.	
130°C	10 min	
150°C	5 min	

Pot life is 2 Days @ 25°C min. The adhesive in used syringe may be sealed and stored in freezer for more useful dispensing life.
 For optimum electrical conductivity, post cure the adhesive at 150C for 2 hours.

SHELF LIFE:

Storage temperature	Shelf Life
-40°C	1 yr

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details
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